

42390.P9557

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Mu, et al.

Serial No.: 09/661,899

Filed: September 14, 2000

For: PROCESS FOR FORMING A
DIRECT BUILD-UP LAYER ON AN
ENCAPSULATED DIE PACKAGES
UTILIZING INTERMEDIATE
STRUCTURES (As Amended)

Examiner: A. Chambliss

Group Art Unit: 2814

Attorney Docket No.: 42390.P9557

CERTIFICATE OF MAILING

I hereby certify that this paper or fee along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231.

1/24/02
Date of Deposit

DEBORAH L. HIGHAM
Signature of registered practitioner or other
person having reasonable basis to expect mailing
to occur on date of deposit shown pursuant to 37
C.F.R. § 1.8(a)(1)(ii)

DEBORAH L. HIGHAM
Typed/printed name of person whose signature is
contained above

3/19/04

PRELIMINARY AMENDMENT

Hon. Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to the examination of the claims on the merits, Applicants respectfully request that the Examiner enter the following amendments:

IN THE SPECIFICATION:

Please delete the title on the cover page and replace with:

PROCESS FOR FORMING A DIRECT BUILD-UP LAYER ON AN
ENCAPSULATED DIE PACKAGES UTILIZING INTERMEDIATE STRUCTURES